

TITLE OF THE INVENTION: WAFER POLISHING DEVICE

ABSTRACT

The present invention discloses a wafer polishing device, which comprises a second
5 pressure medium cavity for detecting pressure changes; a porous disc with a plurality of through
holes, and its lower surface is covered with a flexible single cavity film; a conduction valve unit
for conduction or isolation between the second pressure medium cavity and the third pressure
medium cavity, which at least includes a conduction valve seat, a conduction valve and an elastic
part. The lower end of the conduction valve seat extends into the through hole, and protrudes
10 from the lower end face of the conduction valve seat; The conduction valve seat, the porous disc
and the covered flexible single cavity membrane combined to form the third pressure medium
cavity; a first pressure medium cavity.

FIG. 1